



Device Material Content

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Package: 36WLCSP
Total Device Weight: 0.00895

Grams

with SnAgCu Solder Balls

MSL: 1
Peak Reflow Temp 260°C

Component	% of total package weight	weight (g)	substance	% of total package weight	weight (g)	CAS #	Notes/Assumptions
Die	57.55%	0.005148	Silicon	57.55%	0.005148	7440-21-3	
Repassivation	0.94%	0.000085	HD8820				
			4-Butyrolactone	0.47%	0.000042	96-48-0	45-55% (assumed 50% here)
			Polyamide	0.33%	0.000030	Trade Secret	30-40% (assumed 35% here)
			1-Methoxy-2-propyl acetate	0.05%	0.000004	108-65-6	1-10% (assumed 5% here)
			Photo Active Compound	0.05%	0.000004	Trade Secret	1-10% (assumed 5% here)
			Proprietary Additives	0.05%	0.000004	Trade Secret	1-10% (assumed 5% here)
RDL metalization	11.29%	0.001010	RDL-Ti	0.09%	0.000008	7440-32-6	Ti (0.81%)
			RDL-Cu	0.36%	0.000032	7440-50-8	Cu (0.32%)
			RDL-Cu	10.84%	0.000970	7440-50-8	Cu (99.99%)
UBM	10.44%	0.000934	UBM-Ti	0.06%	0.000006	7440-32-6	Ti (0.61%)
			UBM-Cu	0.25%	0.000023	7440-50-8	Ti (2.42%)
			UBM-Cu	10.13%	0.000906	7440-50-8	Cu (99.96%)
Solder Ball	16.71%	0.001494	SAC405				
			Tin (Sn)	15.96%	0.001427	7440-31-5	95.50%
			Silver (Ag)	0.67%	0.000060	7440-22-4	4.00%
			Copper (Cu)	0.08%	0.000007	7440-50-8	0.50%
BSL	3.07%	0.000274	LC2350				
			Polyethylene Terephthalate	2.15%	0.000192	25038-59-9	60-80% (assumed 70% here)
			Silica	0.54%	0.000048	Trade Secret	10-25% (assumed 17.5% here)
			Epoxy Resin	0.18%	0.000016	Trade Secret	3-10% (assumed 6%)
			Acrylic Resin	0.18%	0.000016	Trade Secret	3-10% (assumed 6%)
			Carbon Black	0.02%	0.000001	Trade Secret	<1% (assume 0.5%)

Notes:

The values listed above are nominal values based on studies of representatives of this particular package type, and are believed to be as accurate as possible.

Constituent substances and proportions in epoxy materials are before curing.

The information provided above is representative of the package as of the date listed, and is subject to change at any time.

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